PHOTOFINER
フォトファイナー

PFR®-800 AUS® SR1 (Trial #64329)

FC 用現像型ソルダーレジストドライフィルム

Dry Film Solder Resist for Flip Chip Substrate Application

- **投影露光 / 直描露光対応**
  Product line up suitable to various exposure units (Projection, Direct Imaging)
- **高 Tg/ 低 CTE 材：優れた TCT/PCT 耐性**
  Tough resin structure with High Tg/Low CTE for TCT and PCT resistance
- **高精細での優れた電気特性**
  Electrical reliability: No migration failure with L/S 15/10μm after 200hrs, 12V, 130℃/85%Rh

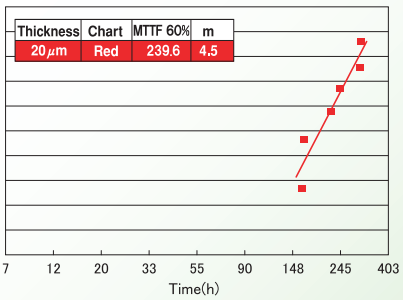
仕様 Specification

膜厚 Resin thickness	20μm (standard) - Adjustable
色調 Color	Green
保管条件 Storage condition	Below –15℃
推奨硬化条件 Recommended curing condition	160℃, 60min.

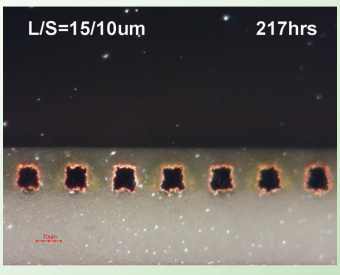
特性 Properties

ガラス転移点 Tg *TMA method		130 - 140 ℃
線膨張係数 CTE	α1	40 – 45 ppm
弾性率 Young's modulus		3.5 - 4.0 GPa
破壊強度 Tensile strength		70 - 75 MPa
破壊伸び率 Elongation		3.5 – 4.0 %
感度 Photosensitivity		350 mJ/cm²
解像性 SRO resolution		50 μm in diameter
PCT 耐性 (121℃, 2 .1atm, 100%Rh, 200hrs)		No peeling
HAST 耐性 (130℃, 85%Rh, 12V, 168hrs, L/S=15/10μm)		No migration
TCT 耐性 (-65 ⇔ 150℃, 1000cycles)		Pass

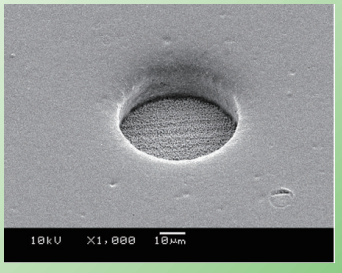
Weibull plot in BHAST
L/S15/10μm, 130℃/85% 12V



After 217hrs HAST 130℃/85% 12V



SRO 50μm by USIO Projector 350 mJ/cm²



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